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# Anisotropic EBSD Nickel data simulation and high temperature grain boundary migration study in 2D

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MCP 1



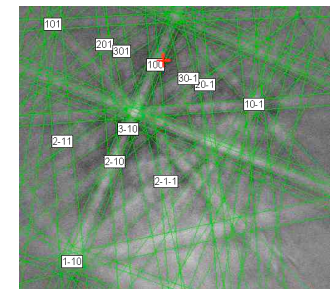
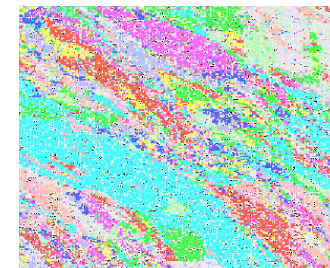
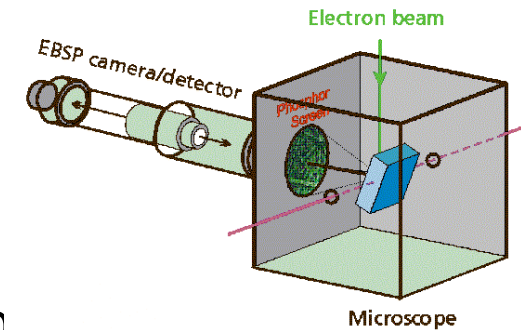
# In this talk...

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- Experimental Nickel data
  - 1941 orientation combinations
  - Refined by misorientation calculation
  - MPM simulation
- Grain boundary mobility
  - Srolovitz's low temperature work review
  - High temperature study

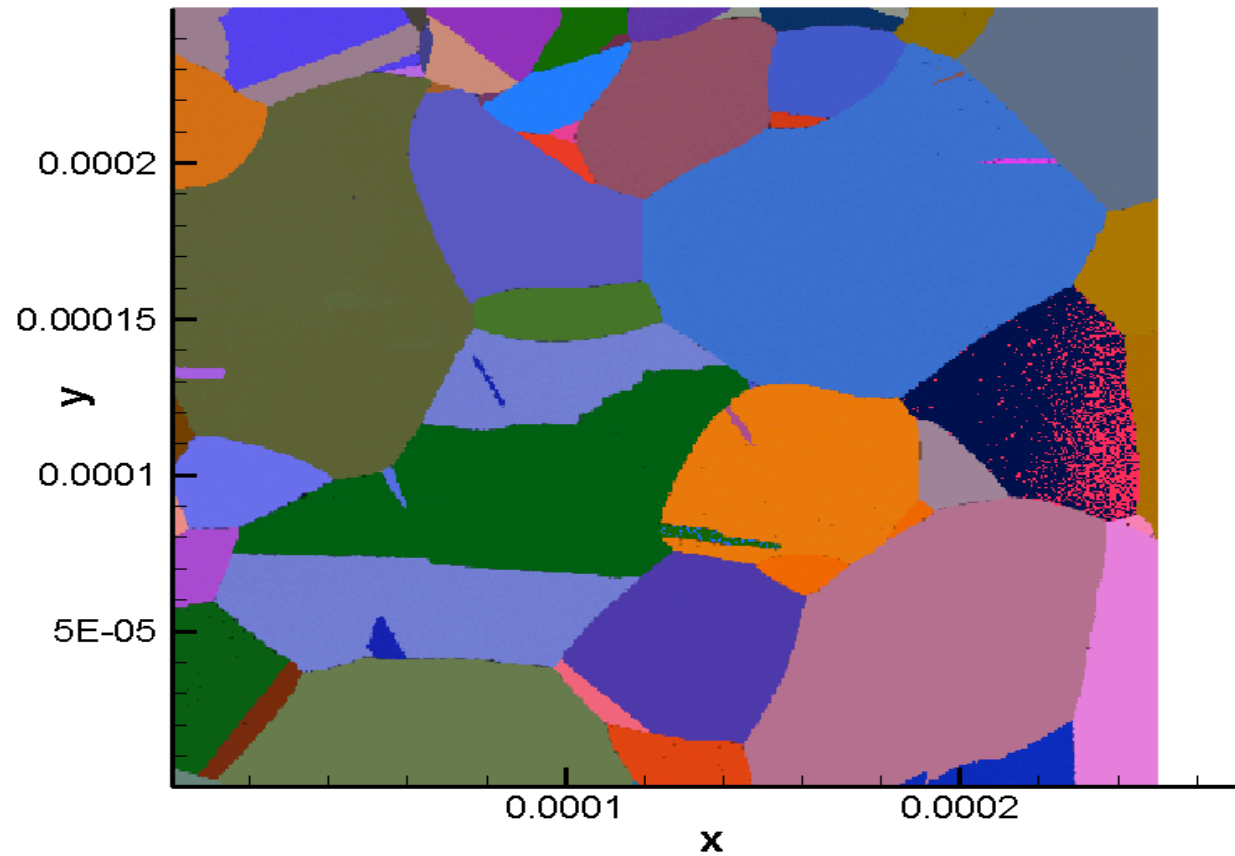
# EBSD summary:

- EBSD is a commercially available tool for studying the crystallography and plastic strain state of crystalline materials.
- EBSD can be used to map grain orientation and to map grain boundaries.
- EBSD can be used to identify unknown crystalline phases by matching patterns and in conjunction with X-ray microanalysis
- EBSD techniques are being developed to map plastic deformation in metallic microstructures.



# Raw Nickel data

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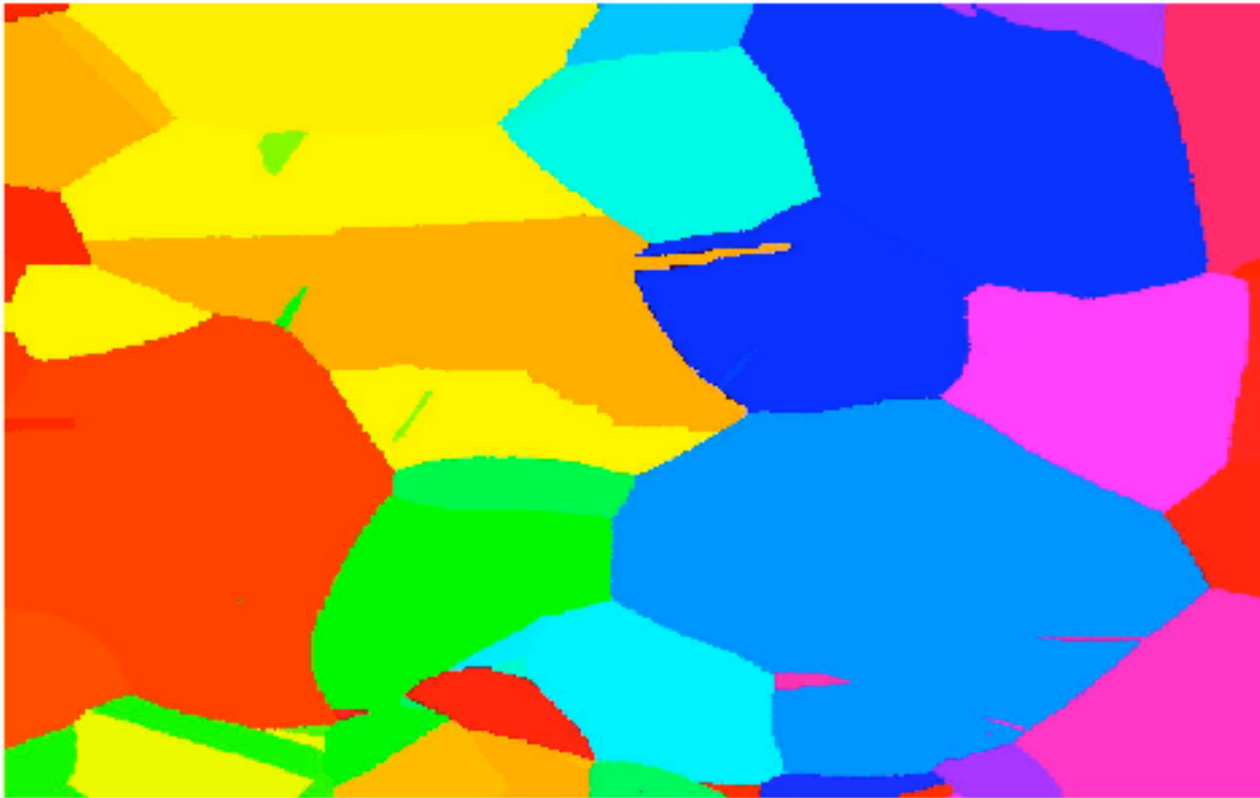


MCP 4



# Refined Nickel data

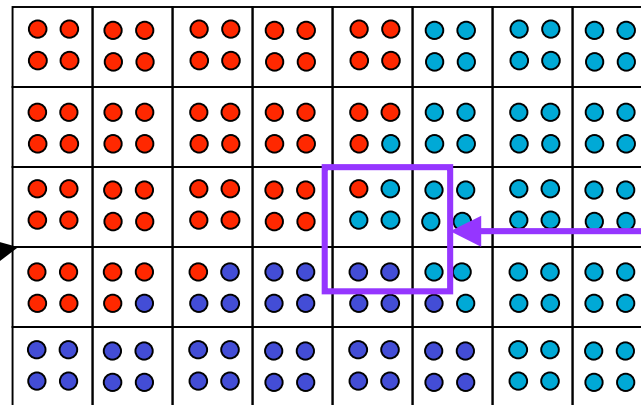
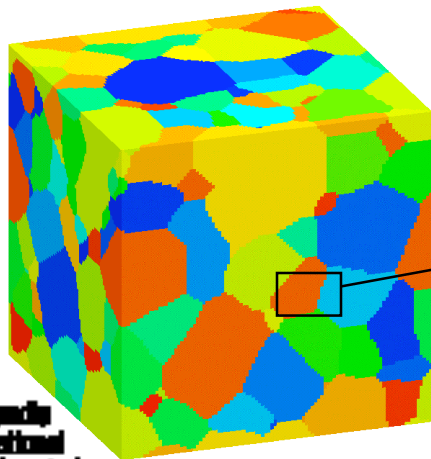
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# MPM coupled with KMC

- **Material Point Method (MPM)**
  - lagrangian particle & cell method
    - continuum mechanics
    - 'solution' at material points (mass, momentum, energy, stress)
    - strain tensor enables use of traditional material response models
- **Lagrangian grid**
  - simplifies traction bc and HMC particle indexing
  - No particle cell crossing issues
- **Hybrid Monte Carlo (HMC) for grain growth**
  - Map microstructure onto particles\*

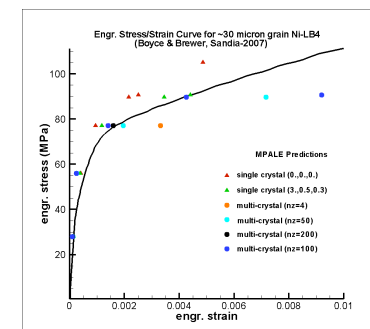
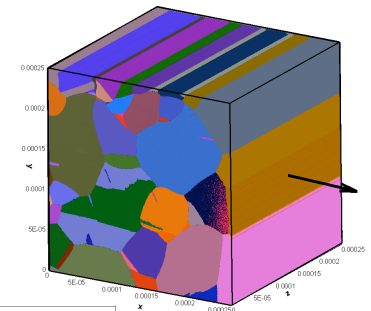
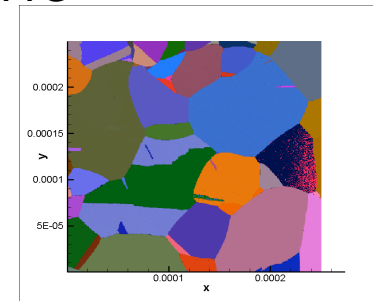
\* Particles contain information about crystallographic orientation, as well as mechanical state.



- Determine particle free energies based on elastic strain energy (at individual particle) and surface energy (from particle neighborhood)
- MC decision algorithm

# Comparison with Ni EBSD and uniaxial tension test

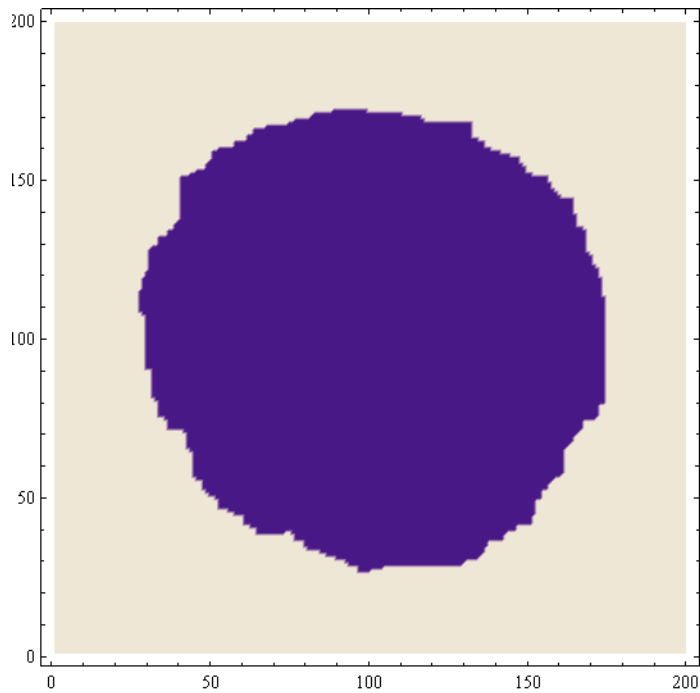
- **Problem:** Given 2D EBSD data for the crystal orientation of a nickel coupon, predict the engineering stress/strain curve
- **Data**
  - 250x250 micron
  - digital data set (500x500 points)
  - ~2000 different Euler angle combinations
- **Issues**
  - data is 2D, crystal slip planes are 3D
  - boundary conditions uncertain
- **Solution Strategy 1**
  - project 2D grains to 3D (columnar grains)
  - results indicate material is too 'soft' at higher stress
  - computational intensive
    - For  $n_z=100$  (aspect ratio=1),
    - 50M computational particles
    - 24hr with 1000p on Redstorm for load curve
      - AMD 2.4 Ghz Opteron processor



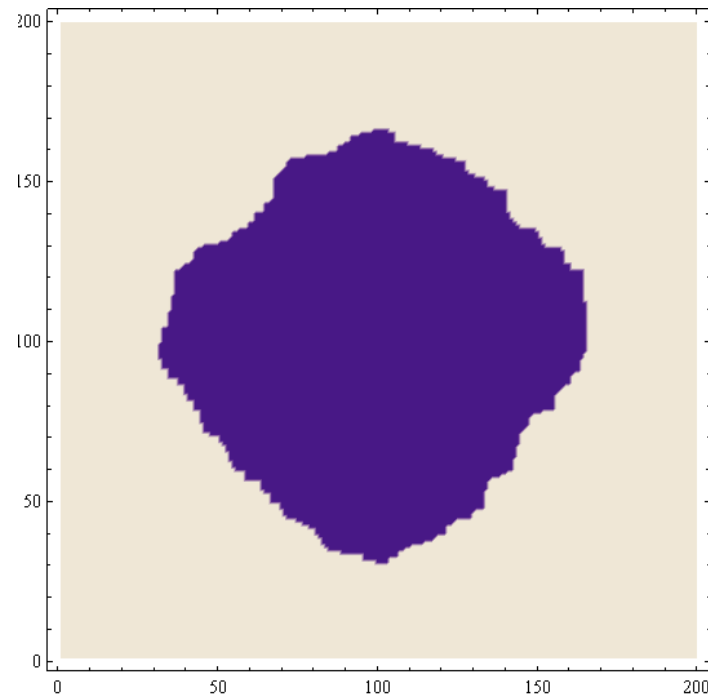
# MC simulation result at $T/T_c=0.3$

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No bulk energy



With bulk energy

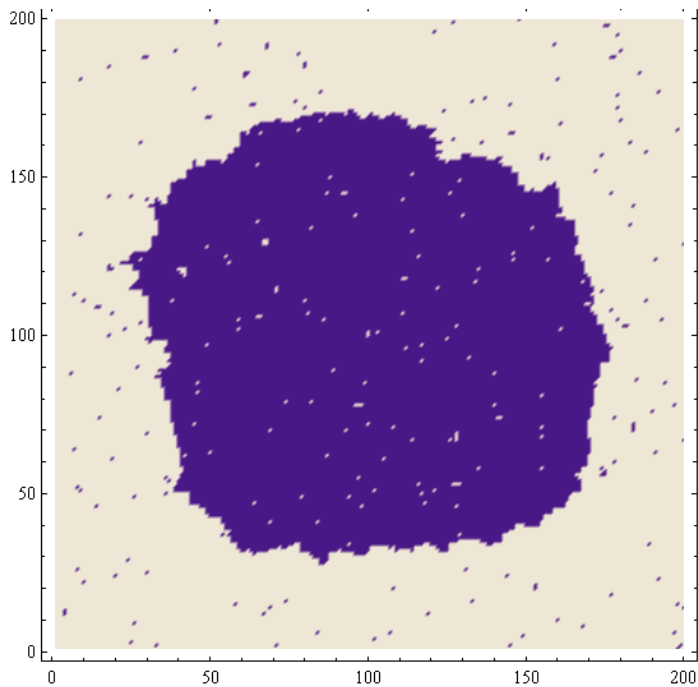




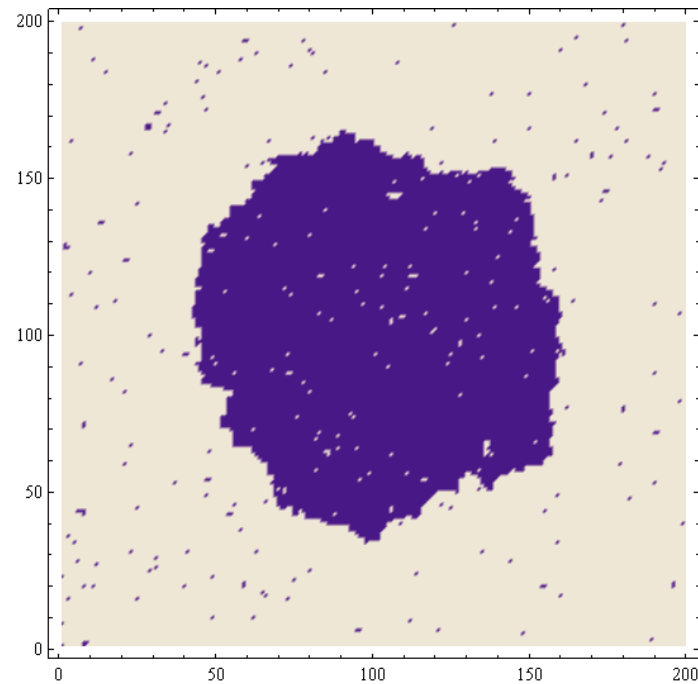
# MC simulation result at $T/T_c=0.7$

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No bulk energy

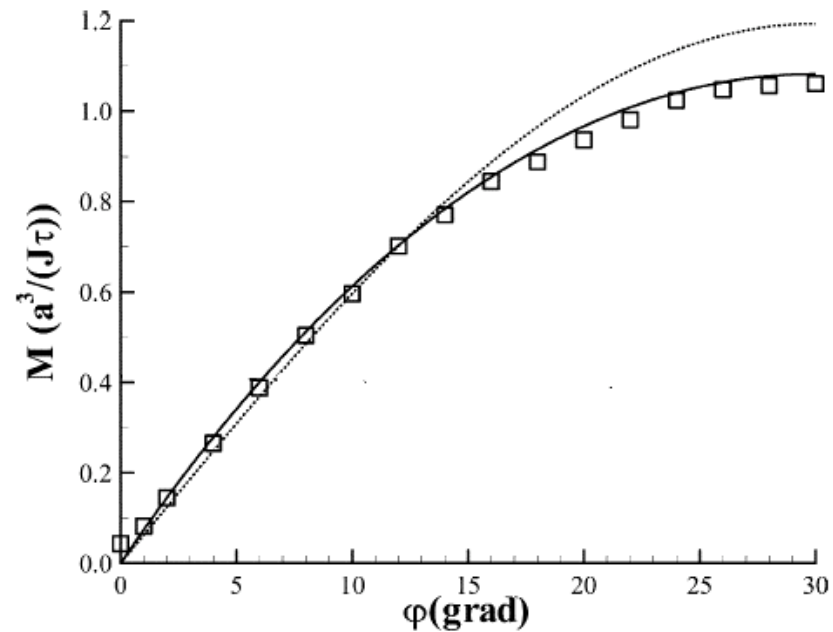
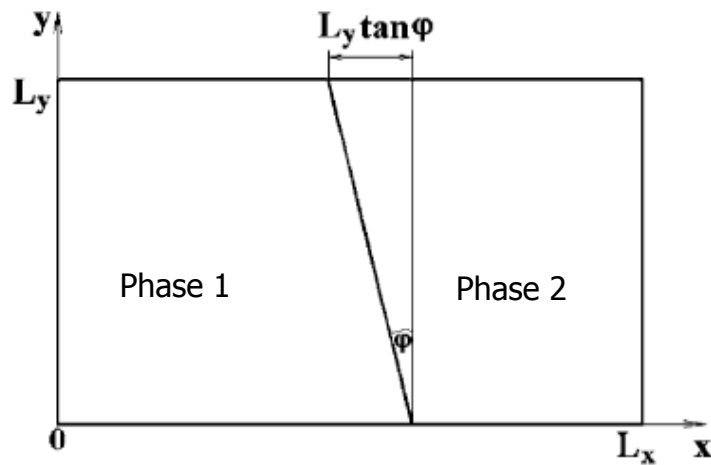


With bulk energy

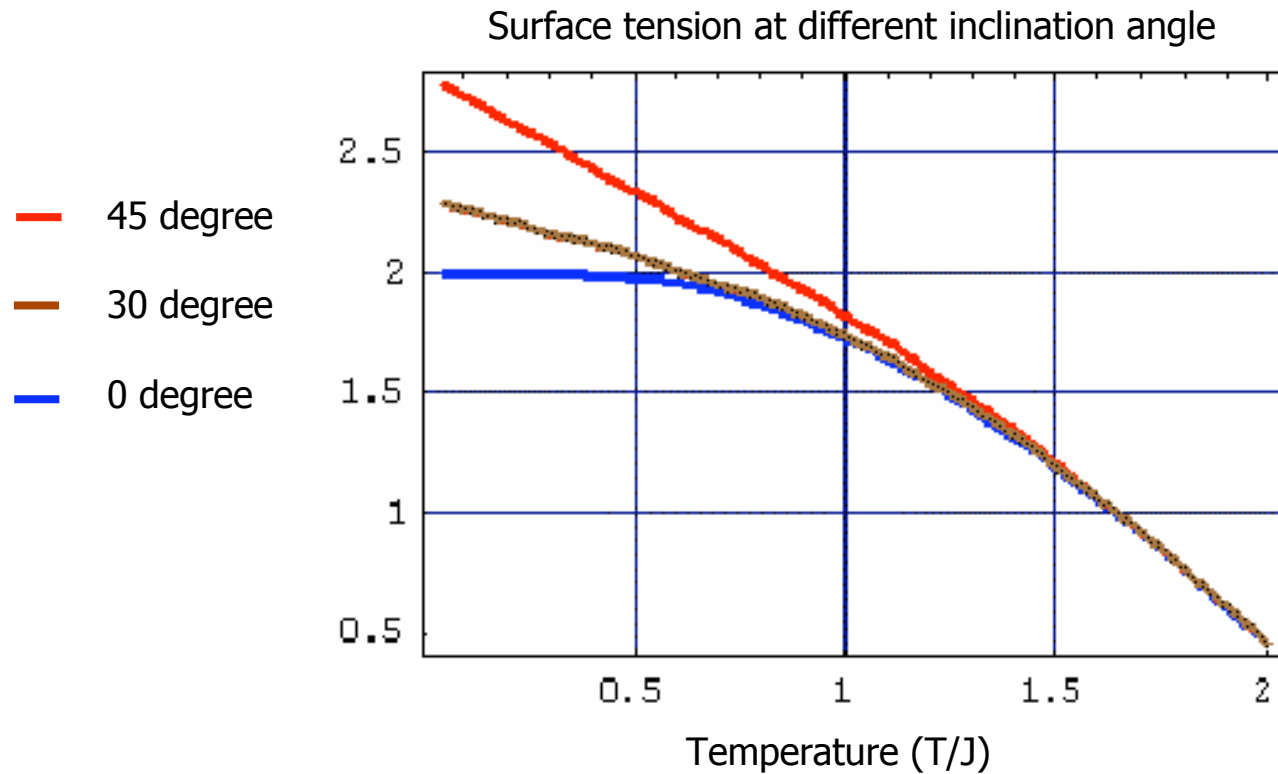


# Grain boundary mobility via MC simulation

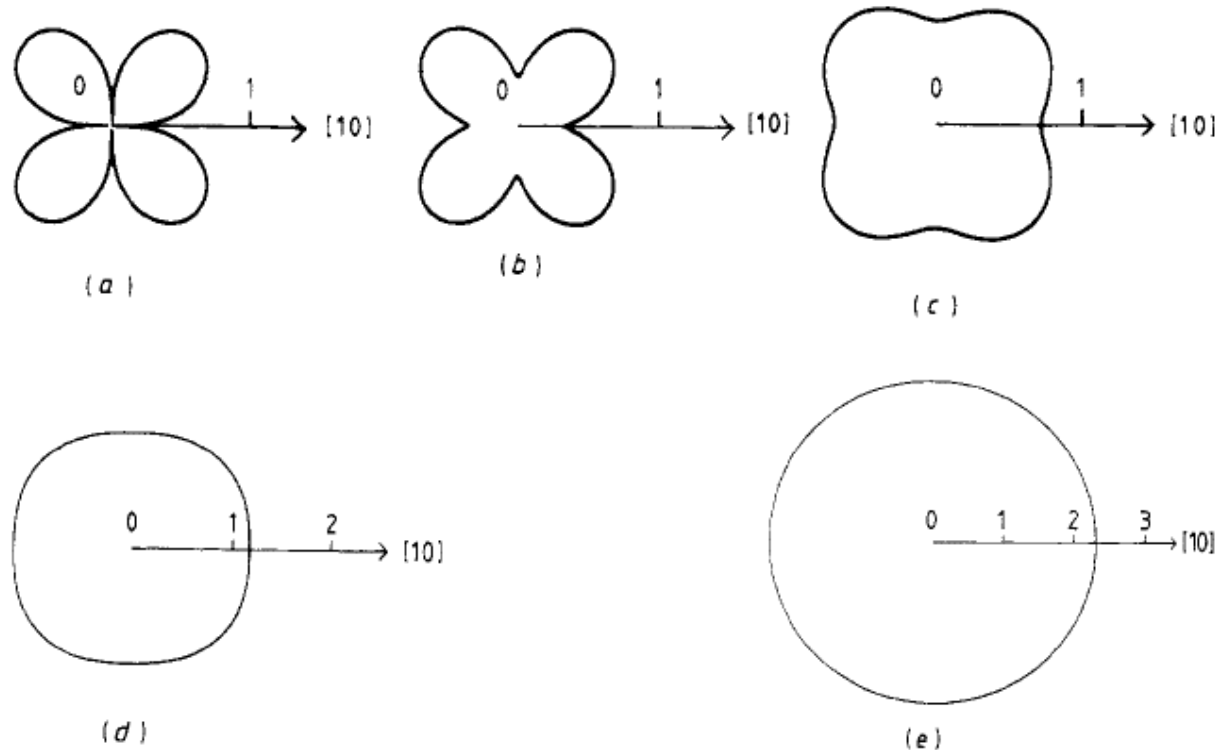
Geometry setting



# Anisotropic surface tension



# Grain boundary stiffness at different T



Inverse square root of grain boundary stiffness. The temperatures are chosen as (a)  $T/T_c=0.1$ , (b)  $T/T_c=0.3$ , (c)  $T/T_c=0.5$ , (d)  $T/T_c=0.7$ , (e)  $T/T_c=0.9$ .

# Conclusion and future research

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- MPM result is consistent with experimental data
- At low temperature, both surface tension and grain boundary mobility are anisotropic
- At high temperature, both surface tension and grain boundary mobility are isotropic
- Grain boundary mobility is independent of driving force type
- KMC option will be turned on to see texture evolution
- Grain boundary mobility study will be extended to 3D

**Thanks.**

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***Any questions?***